

ABSTRACT

An object of the present invention is to provide an epoxy resin exhibiting superior heat resistance, dielectric properties, water resistance, and workability, a resin composition containing the epoxy resin, and a prepreg and a laminated plate. The epoxy resin of the invention is expressed by the following formula. (In the formula, R represents a hydrocarbon group having a carbon number of 1 to 4. m Represents an integer of 1 to 4 and when m is 2 to 4, R's may be the same or different. n Represents a positive number of 1 to 6 on average.) The epoxy resin composition of the invention contains the epoxy resin of the invention and a curing agent.